



2813

PATENT
Atty. Dkt. No. AMAT/6072/CMP/ECP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#9/ *Electronics*
12/17/02
VB

In re Application of:
Olgado, et al.

Serial No.: 09/981,505

Confirmation No.: 6914

Filed: October 16, 2001

For: PLANARIZATION OF METAL
LAYERS ON A SEMI-
CONDUCTOR WAFER
THROUGH NON-CONTACT DE-
PLATING AND CONTROL WITH
ENDPOINT DETECTION

Group Art Unit: 2813

Examiner: Thanh T. Nguyen

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BOX NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>11/18</u> , 2002 with the United States Postal Service	
as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.	
<u>11/18/02</u> Date	<u>Keith R. Zehr</u> Signature

Dear Sir:

RESPONSE TO RESTRICTION REQUIREMENT DATED OCTOBER 18, 2002

In response to the Restriction Requirement dated October 18, 2002, having a shortened statutory period for response set to expire on November 18, 2002, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/6072/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE SPECIFICATION:

Please replace paragraph [0038] with the following paragraph: